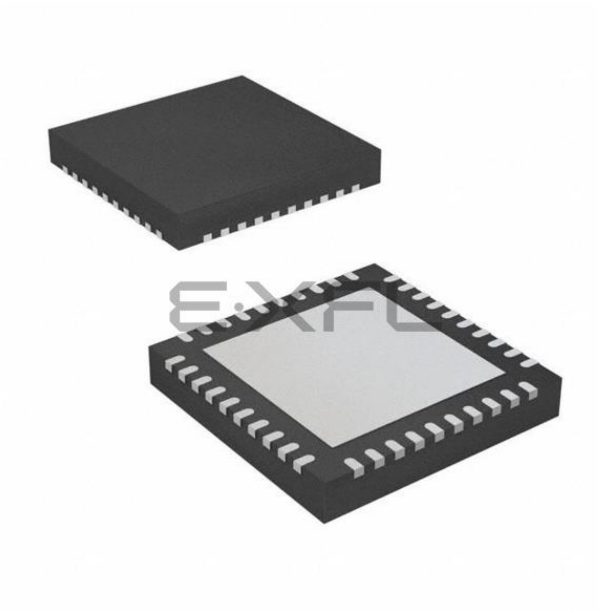

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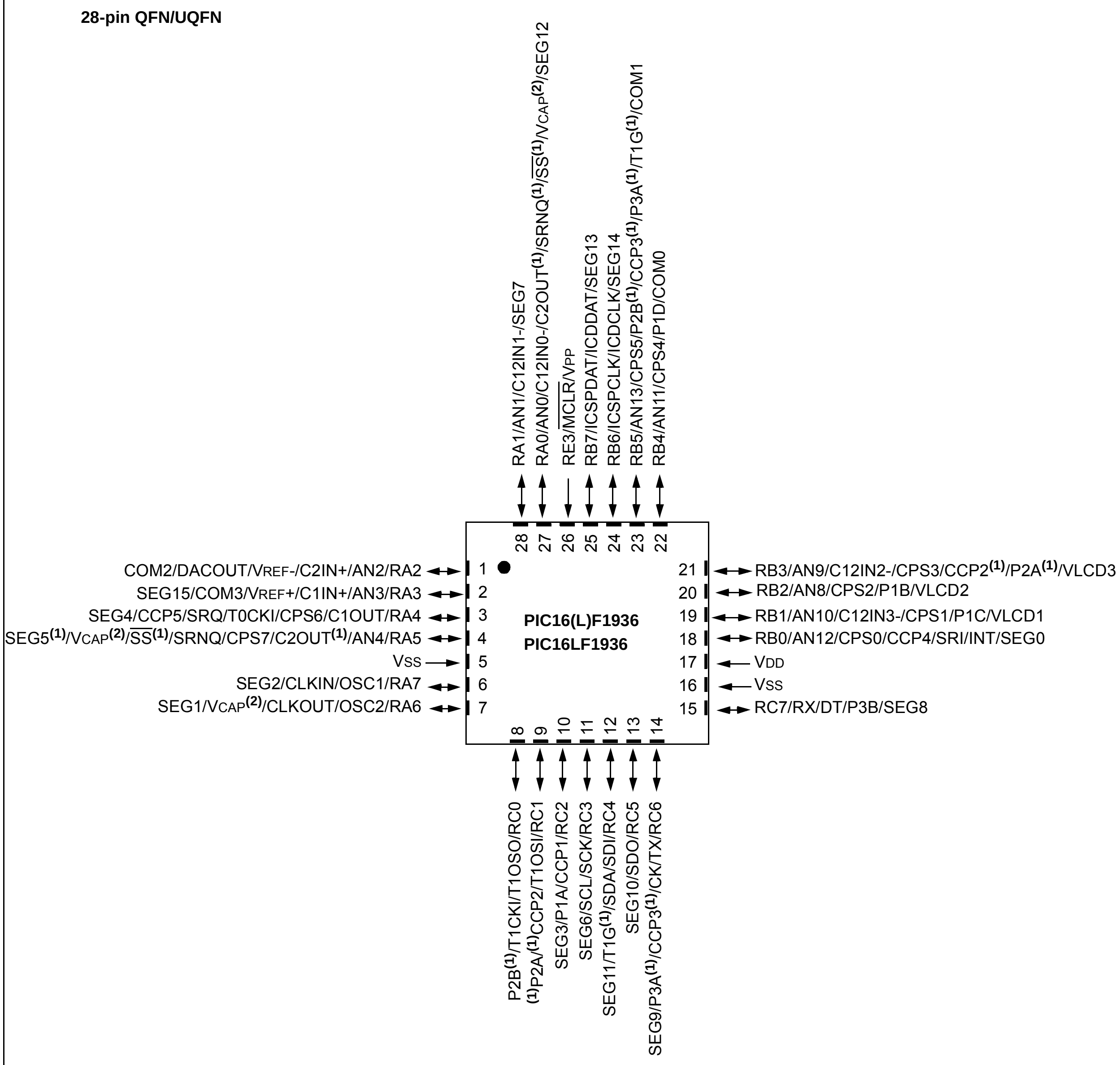
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	40-UFQFN Exposed Pad
Supplier Device Package	40-UQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1937t-i-mv

Pin Diagram – 28-Pin QFN/UQFN (PIC16(L)F1936)



Note 1: Pin function is selectable via the APFCON register.

2: PIC16F1936 devices only.

TABLE 1-2: PIC16(L)F1934/6/7 PINOUT DESCRIPTION (CONTINUED)

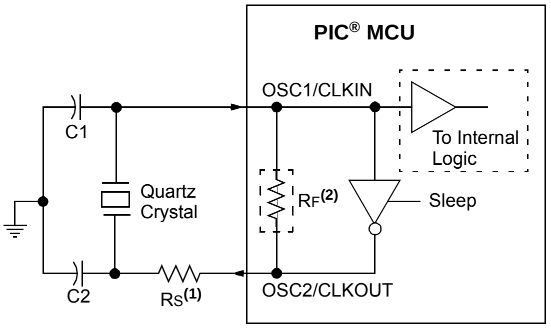
Name	Function	Input Type	Output Type	Description
RA6/OSC2/CLKOUT/VCAP(2)/SEG1	RA6	TTL	CMOS	General purpose I/O.
	OSC2	—	XTAL	Crystal/Resonator (LP, XT, HS modes).
	CLKOUT	—	CMOS	FOSC/4 output.
	VCAP	Power	Power	Filter capacitor for Voltage Regulator (PIC16F1934/6/7 only).
	SEG1	—	AN	LCD Analog output.
RA7/OSC1/CLKIN/SEG2	RA7	TTL	CMOS	General purpose I/O.
	OSC1	XTAL	—	Crystal/Resonator (LP, XT, HS modes).
	CLKIN	CMOS	—	External clock input (EC mode).
	SEG2	—	AN	LCD Analog output.
RB0/AN12/CPS0/CCP4/SRI/INT/SEG0	RB0	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN12	AN	—	A/D Channel 12 input.
	CPS0	AN	—	Capacitive sensing input 0.
	CCP4	ST	CMOS	Capture/Compare/PWM4.
	SRI	—	ST	SR Latch input.
	INT	ST	—	External interrupt.
	SEG0	—	AN	LCD analog output.
RB1/AN10/C12IN3-/CPS1/P1C/VLCD1	RB1	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN10	AN	—	A/D Channel 10 input.
	C12IN3-	AN	—	Comparator C1 or C2 negative input.
	CPS1	AN	—	Capacitive sensing input 1.
	P1C	—	CMOS	PWM output.
	VLCD1	AN	—	LCD analog input.
RB2/AN8/CPS2/P1B/VLCD2	RB2	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN8	AN	—	A/D Channel 8 input.
	CPS2	AN	—	Capacitive sensing input 2.
	P1B	—	CMOS	PWM output.
	VLCD2	AN	—	LCD analog input.
RB3/AN9/C12IN2-/CPS3/CCP2(1)/P2A(1)/VLCD3	RB3	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN9	AN	—	A/D Channel 9 input.
	C12IN2-	AN	—	Comparator C1 or C2 negative input.
	CPS3	AN	—	Capacitive sensing input 3.
	CCP2	ST	CMOS	Capture/Compare/PWM2.
	P2A	—	CMOS	PWM output.
	VLCD3	AN	—	LCD analog input.

Legend:
AN = Analog input or output
TTL = TTL compatible input
HV = High Voltage
CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
XTAL = Crystal
OD = Open Drain
I^2C™ = Schmitt Trigger input with I^2C levels

Note 1: Pin function is selectable via the APFCON register.
2: PIC16F1934/6/7 devices only.
3: PIC16(L)F1936 devices only.
4: PORTD is available on PIC16(L)F1934/7 devices only.
5: RE<2:0> are available on PIC16(L)F1934/7 devices only.

NOTES:

FIGURE 5-3: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)



Note 1: A series resistor (R_S) may be required for quartz crystals with low drive level.

2: The value of R_F varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

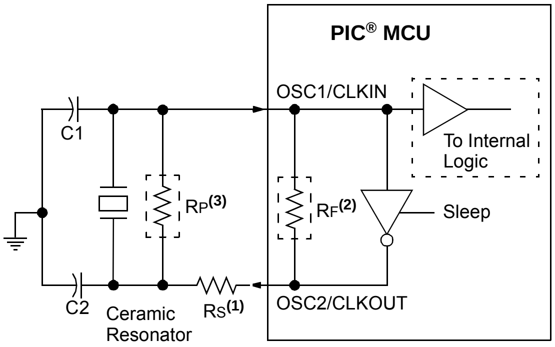
Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the V_{DD} and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Applications Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)

FIGURE 5-4: CERAMIC RESONATOR OPERATION (XT OR HS MODE)



Note 1: A series resistor (R_S) may be required for ceramic resonators with low drive level.

2: The value of R_F varies with the Oscillator mode selected (typically between 2 MΩ to 10 MΩ).

3: An additional parallel feedback resistor (R_P) may be required for proper ceramic resonator operation.

5.2.1.3 Oscillator Start-up Timer (OST)

If the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module.

In order to minimize latency between external oscillator start-up and code execution, the Two-Speed Clock Start-up mode can be selected (see **Section 5.4 "Two-Speed Clock Start-up Mode"**).

5.2.1.4 4X PLL

The oscillator module contains a 4X PLL that can be used with both external and internal clock sources to provide a system clock source. The input frequency for the 4X PLL must fall within specifications. See the PLL Clock Timing specifications in the applicable Electrical Specifications Chapter.

The 4X PLL may be enabled for use by one of two methods:

1. Program the PLLEN bit in Configuration Word 2 to a '`1`'.
2. Write the SPLLEN bit in the OSCCON register to a '`1`'. If the PLLEN bit in Configuration Word 2 is programmed to a '`1`', then the value of SPLLEN is ignored.

5.2.2 INTERNAL CLOCK SOURCES

The device may be configured to use the internal oscillator block as the system clock by performing one of the following actions:

- Program the FOSC<2:0> bits in Configuration Word 1 to select the INTOSC clock source, which will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to the internal oscillator during run-time. See **Section 5.3 "Clock Switching"**for more information.

In **INTOSC** mode, OSC1/CLKIN is available for general purpose I/O. OSC2/CLKOUT is available for general purpose I/O or CLKOUT.

The function of the OSC2/CLKOUT pin is determined by the state of the $\overline{\text{CLKOUTEN}}$ bit in Configuration Word 1.

The internal oscillator block has two independent oscillators and a dedicated Phase-Lock Loop, HFPLL that can produce one of three internal system clock sources.

1. The **HFINTOSC** (High-Frequency Internal Oscillator) is factory calibrated and operates at 16 MHz. The HFINTOSC source is generated from the 500 kHz MFINTOSC source and the dedicated Phase-Lock Loop, HFPLL. The frequency of the HFINTOSC can be user-adjusted via software using the OSCTUNE register (Register 5-3).
2. The **MFINTOSC** (Medium-Frequency Internal Oscillator) is factory calibrated and operates at 500 kHz. The frequency of the MFINTOSC can be user-adjusted via software using the OSCTUNE register (Register 5-3).
3. The **LFINTOSC** (Low-Frequency Internal Oscillator) is uncalibrated and operates at 31 kHz.

5.2.2.1 HFINTOSC

The High-Frequency Internal Oscillator (HFINTOSC) is a factory calibrated 16 MHz internal clock source. The frequency of the HFINTOSC can be altered via software using the OSCTUNE register (Register 5-3).

The output of the HFINTOSC connects to a postscaler and multiplexer (see Figure 5-1). One of nine frequencies derived from the HFINTOSC can be selected via software using the IRCF<3:0> bits of the OSCCON register. See **Section 5.2.2.7 "Internal Oscillator Clock Switch Timing"** for more information.

The HFINTOSC is enabled by:

- Configure the IRCF<3:0> bits of the OSCCON register for the desired HF frequency, and
- FOSC<2:0> = `100`, or
- Set the System Clock Source (SCS) bits of the OSCCON register to '`1x`'.

The High-Frequency Internal Oscillator Ready bit (HFIOFR) of the OSCSTAT register indicates when the HFINTOSC is running and can be utilized.

The High-Frequency Internal Oscillator Status Locked bit (HFIOFL) of the OSCSTAT register indicates when the HFINTOSC is running within 2% of its final value.

The High-Frequency Internal Oscillator Status Stable bit (HFIOFS) of the OSCSTAT register indicates when the HFINTOSC is running within 0.5% of its final value.

5.2.2.2 MFINTOSC

The Medium-Frequency Internal Oscillator (MFINTOSC) is a factory calibrated 500 kHz internal clock source. The frequency of the MFINTOSC can be altered via software using the OSCTUNE register (Register 5-3).

The output of the MFINTOSC connects to a postscaler and multiplexer (see Figure 5-1). One of nine frequencies derived from the MFINTOSC can be selected via software using the IRCF<3:0> bits of the OSCCON register. See **Section 5.2.2.7 "Internal Oscillator Clock Switch Timing"** for more information.

The MFINTOSC is enabled by:

- Configure the IRCF<3:0> bits of the OSCCON register for the desired HF frequency, and
- FOSC<2:0> = `100`, or
- Set the System Clock Source (SCS) bits of the OSCCON register to '`1x`'

The Medium-Frequency Internal Oscillator Ready bit (MFIOFR) of the OSCSTAT register indicates when the MFINTOSC is running and can be utilized.

5.2.2.6 32 MHz Internal Oscillator Frequency Selection

The Internal Oscillator Block can be used with the 4X PLL associated with the External Oscillator Block to produce a 32 MHz internal system clock source. The following settings are required to use the 32 MHz internal clock source:

- The FOSC bits in Configuration Word 1 must be set to use the INTOSC source as the device system clock (FOSC<2:0> = `100`).
- The SCS bits in the OSCCON register must be cleared to use the clock determined by FOSC<2:0> in Configuration Word 1 (SCS<1:0> = `00`).
- The IRCF bits in the OSCCON register must be set to the 8 MHz HFINTOSC set to use (IRCF<3:0> = `1110`).
- The SPLLEN bit in the OSCCON register must be set to enable the 4xPLL, or the PLLEN bit of the Configuration Word 2 must be programmed to a ‘`1`’.

Note:	When using the PLLEN bit of the Configuration Word 2, the 4xPLL cannot be disabled by software and the 8 MHz HFINTOSC option will no longer be available.

The 4xPLL is not available for use with the internal oscillator when the SCS bits of the OSCCON register are set to ‘`1x`’. The SCS bits must be set to ‘`00`’ to use the 4xPLL with the internal oscillator.

5.2.2.7 Internal Oscillator Clock Switch Timing

When switching between the HFINTOSC, MFINTOSC and the LFINTOSC, the new oscillator may already be shut down to save power (see Figure 5-7). If this is the case, there is a delay after the IRCF<3:0> bits of the OSCCON register are modified before the frequency selection takes place. The OSCSTAT register will reflect the current active status of the HFINTOSC, MFINTOSC and LFINTOSC oscillators. The sequence of a frequency selection is as follows:

1. IRCF<3:0> bits of the OSCCON register are modified.
2. If the new clock is shut down, a clock start-up delay is started.
3. Clock switch circuitry waits for a falling edge of the current clock.
4. The current clock is held low and the clock switch circuitry waits for a rising edge in the new clock.
5. The new clock is now active.
6. The OSCSTAT register is updated as required.
7. Clock switch is complete.

See Figure 5-7 for more details.

If the internal oscillator speed is switched between two clocks of the same source, there is no start-up delay before the new frequency is selected. Clock switching time delays are shown in Table 5-1.

Start-up delay specifications are located in the oscillator tables in the applicable Electrical Specifications Chapter.

6.1 Power-on Reset (POR)

The POR circuit holds the device in Reset until VDD has reached an acceptable level for minimum operation. Slow rising VDD, fast operating speeds or analog performance may require greater than minimum VDD. The PWRT, BOR or $\overline{\text{MCLR}}$ features can be used to extend the start-up period until all device operation conditions have been met.

6.1.1 POWER-UP TIMER (PWRT)

The Power-up Timer provides a nominal 64 ms time-out on POR or Brown-out Reset.

The device is held in Reset as long as PWRT is active. The PWRT delay allows additional time for the VDD to rise to an acceptable level. The Power-up Timer is enabled by clearing the $\overline{\text{PWRTE}}$ bit in Configuration Word 1.

The Power-up Timer starts after the release of the POR and BOR.

For additional information, refer to Application Note AN607, *“Power-up Trouble Shooting”* (DS00607).

6.2 Brown-Out Reset (BOR)

The BOR circuit holds the device in Reset when VDD reaches a selectable minimum level. Between the POR and BOR, complete voltage range coverage for execution protection can be implemented.

The Brown-out Reset module has four operating modes controlled by the BOREN<1:0> bits in Configuration Word 1. The four operating modes are:

- BOR is always on
- BOR is off when in Sleep
- BOR is controlled by software
- BOR is always off

Refer to Table 6-3 for more information.

The Brown-out Reset voltage level is selectable by configuring the BORV bit in Configuration Word 2.

A VDD noise rejection filter prevents the BOR from triggering on small events. If VDD falls below VBOR for a duration greater than parameter TBORDC, the device will reset. See Figure 6-2 for more information.

TABLE 6-1: BOR OPERATING MODES

BOREN<1:0>	SBOREN	Device Mode	BOR Mode	Device Operation upon release of POR	Device Operation upon wake- up from Sleep
`11`	X	X	Active	Waits for BOR ready[1]	
`10`	X	Awake	Active	Waits for BOR ready	
		Sleep	Disabled		
`01`	`1`	X	Active	Begins immediately	
	`0`		Disabled	Begins immediately	
`00`	X	X	Disabled	Begins immediately	

Note 1: Even though this case specifically waits for the BOR, the BOR is already operating, so there is no delay in start-up.

6.2.1 BOR IS ALWAYS ON

When the BOREN bits of Configuration Word 1 are set to ‘`11`’, the BOR is always on. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is active during Sleep. The BOR does not delay wake-up from Sleep.

6.2.2 BOR IS OFF IN SLEEP

When the BOREN bits of Configuration Word 1 are set to ‘`10`’, the BOR is on, except in Sleep. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is not active during Sleep. The device wake-up will be delayed until the BOR is ready.

6.2.3 BOR CONTROLLED BY SOFTWARE

When the BOREN bits of Configuration Word 1 are set to ‘`01`’, the BOR is controlled by the SBOREN bit of the BORCON register. The device start-up is not delayed by the BOR ready condition or the VDD level.

BOR protection begins as soon as the BOR circuit is ready. The status of the BOR circuit is reflected in the BORRDY bit of the BORCON register.

BOR protection is unchanged by Sleep.

NOTES:

9.0 POWER-DOWN MODE (SLEEP)

The Power-down mode is entered by executing a `SLEEP` instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{\text{PD}}$ bit of the STATUS register is cleared.
3. $\overline{\text{TO}}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 oscillator is unaffected and peripherals that operate from it may continue operation in Sleep.
7. ADC is unaffected, if the dedicated FRC clock is selected.
8. Capacitive Sensing oscillator is unaffected.
9. I/O ports maintain the status they had before `SLEEP` was executed (driving high, low or high-impedance).
10. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using Timer1 oscillator

I/O pins that are high-impedance inputs should be pulled to V_{DD} or V_{SS} externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include modules such as the DAC and FVR modules. See **Section 17.0 “Digital-to-Analog Converter (DAC) Module”** and **Section 14.0 “Fixed Voltage Reference (FVR)”** for more information on these modules.

9.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{\text{MCLR}}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 6.10 “Determining the Cause of a Reset”**.

When the `SLEEP` instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the `SLEEP` instruction. If the GIE bit is enabled, the device executes the instruction after the `SLEEP` instruction, the device will call the Interrupt Service Routine. In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have a `NOP` after the `SLEEP` instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

10.1 Independent Clock Source

The WDT derives its time base from the 31 kHz LFINTOSC internal oscillator. Time intervals in this chapter are based on a nominal interval of 1 ms. See the Electrical Specifications Chapters for the LFINTOSC tolerances.

10.2 WDT Operating Modes

The Watchdog Timer module has four operating modes controlled by the WDTE<1:0> bits in Configuration Word 1. See Table 10-1.

10.2.1 WDT IS ALWAYS ON

When the WDTE bits of Configuration Word 1 are set to ‘`11`’, the WDT is always on.

WDT protection is active during Sleep.

10.2.2 WDT IS OFF IN SLEEP

When the WDTE bits of Configuration Word 1 are set to ‘`10`’, the WDT is on, except in Sleep.

WDT protection is not active during Sleep.

10.2.3 WDT CONTROLLED BY SOFTWARE

When the WDTE bits of Configuration Word 1 are set to ‘`01`’, the WDT is controlled by the SWDTEN bit of the WDTCON register.

WDT protection is unchanged by Sleep. See Table 10-1 for more details.

TABLE 10-1: WDT OPERATING MODES

WDTE<1:0>	SWDTEN	Device Mode	WDT Mode
`11`	X	X	Active
`10`	X	Awake	Active
		Sleep	Disabled
`01`	`1`	X	Active
	`0`		Disabled
`00`	X	X	Disabled

10.3 Time-Out Period

The WDTPS bits of the WDTCON register set the time-out period from 1 ms to 256 seconds (nominal). After a Reset, the default time-out period is 2 seconds.

10.4 Clearing the WDT

The WDT is cleared when any of the following conditions occur:

- Any Reset
- `CLRWDT` instruction is executed
- Device enters Sleep
- Device wakes up from Sleep
- Oscillator fail event
- WDT is disabled
- Oscillator Start-up TImer (OST) is running

See Table 10-2 for more information.

10.5 Operation During Sleep

When the device enters Sleep, the WDT is cleared. If the WDT is enabled during Sleep, the WDT resumes counting.

When the device exits Sleep, the WDT is cleared again. The WDT remains clear until the OST, if enabled, completes. See **Section 5.0 “Oscillator Module (With Fail-Safe Clock Monitor)”** for more information on the OST.

When a WDT time-out occurs while the device is in Sleep, no Reset is generated. Instead, the device wakes up and resumes operation. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits in the STATUS register are changed to indicate the event. See **Section 3.0 “Memory Organization”** and STATUS register (**Register 3-1)** for more information.

TABLE 10-2: WDT CLEARING CONDITIONS

Conditions	WDT
WDTE<1:0> = `00`	Cleared
WDTE<1:0> = `01` and SWDTEN = `0`	
WDTE<1:0> = `10` and enter Sleep	
`CLRWDT` Command	
Oscillator Fail Detected	
Exit Sleep + System Clock = T1OSC, EXTRC, INTOSC, EXTCLK	
Exit Sleep + System Clock = XT, HS, LP	Cleared until the end of OST
Change INTOSC divider (IRCF bits)	Unaffected

EXAMPLE 11-3: FLASH PROGRAM MEMORY READ

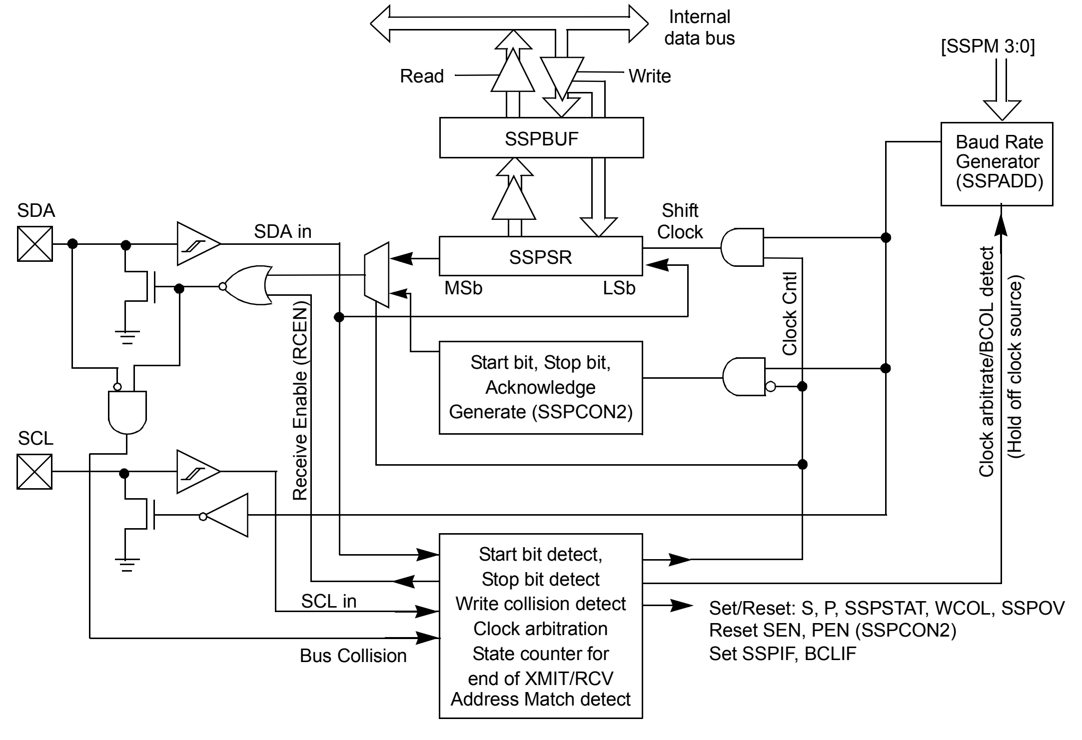
```
* This code block will read 1 word of program
* memory at the memory address:
    PROG_ADDR_HI: PROG_ADDR_LO
*   data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  EEADRL            ; Select Bank for EEPROM registers
    MOVLW    PROG_ADDR_LO      ;
    MOVWF    EEADRL            ; Store LSB of address
    MOVLW    PROG_ADDR_HI      ;
    MOVWL    EEADRH            ; Store MSB of address

    BCF      EECON1,CFGS       ; Do not select Configuration Space
    BSF      EECON1,EEPGD      ; Select Program Memory
    BCF      INTCON,GIE        ; Disable interrupts
    BSF      EECON1,RD         ; Initiate read
    NOP                        ; Executed (Figure 11-1)
    NOP                        ; Ignored (Figure 11-1)
    BSF      INTCON,GIE        ; Restore interrupts

    MOVF     EEDATL,W          ; Get LSB of word
    MOVWF    PROG_DATA_LO      ; Store in user location
    MOVF     EEDATH,W          ; Get MSB of word
    MOVWF    PROG_DATA_HI      ; Store in user location
```

The I^2C interface supports the following modes and features:

- Master mode
- Slave mode
- Byte NACKing (Slave mode)
- Limited Multi-master support
- 7-bit and 10-bit addressing
- Start and Stop interrupts
- Interrupt masking
- Clock stretching
- Bus collision detection
- General call address matching
- Address masking
- Address Hold and Data Hold modes
- Selectable SDA hold times

Figure 24-2 is a block diagram of the I^2C interface module in Master mode. Figure 24-3 is a diagram of the I^2C interface module in Slave mode.

FIGURE 24-2: MSSP BLOCK DIAGRAM (I^2C™ MASTER MODE)



24.6 I^{2}C Master Mode

Master mode is enabled by setting and clearing the appropriate SSPM bits in the SSPCON1 register and by setting the SSPEN bit. In Master mode, the SDA and SCK pins must be configured as inputs. The MSSP peripheral hardware will override the output driver TRIS controls when necessary to drive the pins low.

Master mode of operation is supported by interrupt generation on the detection of the Start and Stop conditions. The Stop (P) and Start (S) bits are cleared from a Reset or when the MSSP module is disabled. Control of the I^{2}C bus may be taken when the P bit is set, or the bus is Idle.

In Firmware Controlled Master mode, user code conducts all I^{2}C bus operations based on Start and Stop bit condition detection. Start and Stop condition detection is the only active circuitry in this mode. All other communication is done by the user software directly manipulating the SDA and SCL lines.

The following events will cause the SSP Interrupt Flag bit, SSPIF, to be set (SSP interrupt, if enabled):

- Start condition detected
- Stop condition detected
- Data transfer byte transmitted/received
- Acknowledge transmitted/received
- Repeated Start generated

Note 1: The MSSP module, when configured in I^{2}C Master mode, does not allow queueing of events. For instance, the user is not allowed to initiate a Start condition and immediately write the SSPBUF register to initiate transmission before the Start condition is complete. In this case, the SSPBUF will not be written to and the WCOL bit will be set, indicating that a write to the SSPBUF did not occur

2: When in Master mode, Start/Stop detection is masked and an interrupt is generated when the SEN/PEN bit is cleared and the generation is complete.

24.6.1 I^{2}C MASTER MODE OPERATION

The master device generates all of the serial clock pulses and the Start and Stop conditions. A transfer is ended with a Stop condition or with a Repeated Start condition. Since the Repeated Start condition is also the beginning of the next serial transfer, the I^{2}C bus will not be released.

In Master Transmitter mode, serial data is output through SDA, while SCL outputs the serial clock. The first byte transmitted contains the slave address of the receiving device (7 bits) and the Read/$\overline{\text{Write}}$ (R/$\overline{\text{W}}$) bit. In this case, the R/$\overline{\text{W}}$ bit will be logic ‘`0`’. Serial data is transmitted 8 bits at a time. After each byte is transmitted, an Acknowledge bit is received. Start and Stop conditions are output to indicate the beginning and the end of a serial transfer.

In Master Receive mode, the first byte transmitted contains the slave address of the transmitting device (7 bits) and the R/$\overline{\text{W}}$ bit. In this case, the R/$\overline{\text{W}}$ bit will be logic ‘`1`’. Thus, the first byte transmitted is a 7-bit slave address followed by a ‘`1`’ to indicate the receive bit. Serial data is received via SDA, while SCL outputs the serial clock. Serial data is received 8 bits at a time. After each byte is received, an Acknowledge bit is transmitted. Start and Stop conditions indicate the beginning and end of transmission.

A Baud Rate Generator is used to set the clock frequency output on SCL. See **Section 24.7 “Baud Rate Generator”** for more detail.

25.1.1.5 TSR Status

The TRMT bit of the TXSTA register indicates the status of the TSR register. This is a read-only bit. The TRMT bit is set when the TSR register is empty and is cleared when a character is transferred to the TSR register from the TXREG. The TRMT bit remains clear until all bits have been shifted out of the TSR register. No interrupt logic is tied to this bit, so the user has to poll this bit to determine the TSR status.

Note:	The TSR register is not mapped in data memory, so it is not available to the user.

25.1.1.6 Transmitting 9-Bit Characters

The EUSART supports 9-bit character transmissions. When the TX9 bit of the TXSTA register is set, the EUSART will shift 9 bits out for each character transmitted. The TX9D bit of the TXSTA register is the ninth, and Most Significant, data bit. When transmitting 9-bit data, the TX9D data bit must be written before writing the 8 Least Significant bits into the TXREG. All nine bits of data will be transferred to the TSR shift register immediately after the TXREG is written.

A special 9-bit Address mode is available for use with multiple receivers. See **Section 25.1.2.7 “Address Detection”** for more information on the address mode.

25.1.1.7 Asynchronous Transmission Set-up:

1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 25.3 “EUSART Baud Rate Generator (BRG)”**).
2. Enable the asynchronous serial port by clearing the SYNC bit and setting the SPEN bit.
3. If 9-bit transmission is desired, set the TX9 control bit. A set ninth data bit will indicate that the 8 Least Significant data bits are an address when the receiver is set for address detection.
4. Set SCKP bit if inverted transmit is desired.
5. Enable the transmission by setting the TXEN control bit. This will cause the TXIF interrupt bit to be set.
6. If interrupts are desired, set the TXIE interrupt enable bit of the PIE1 register. An interrupt will occur immediately provided that the GIE and PEIE bits of the INTCON register are also set.
7. If 9-bit transmission is selected, the ninth bit should be loaded into the TX9D data bit.
8. Load 8-bit data into the TXREG register. This will start the transmission.

FIGURE 25-3: ASYNCHRONOUS TRANSMISSION

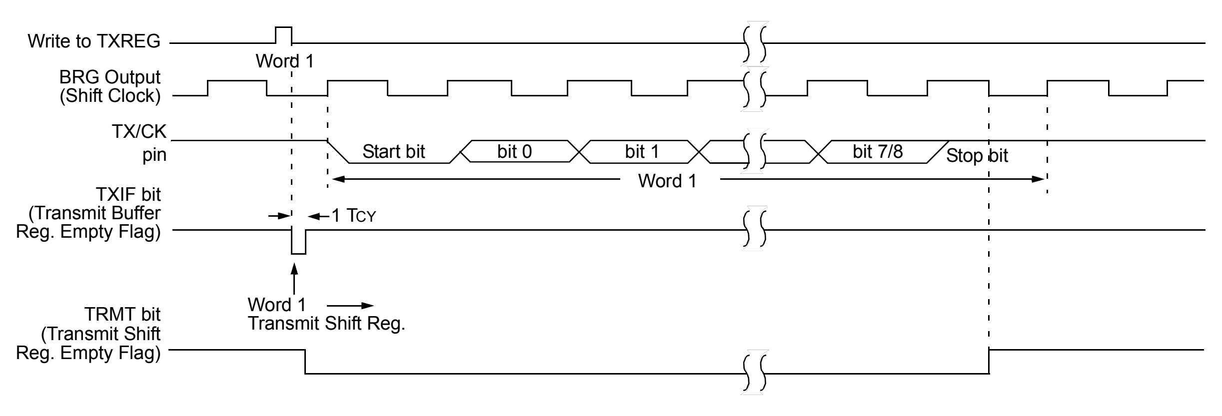
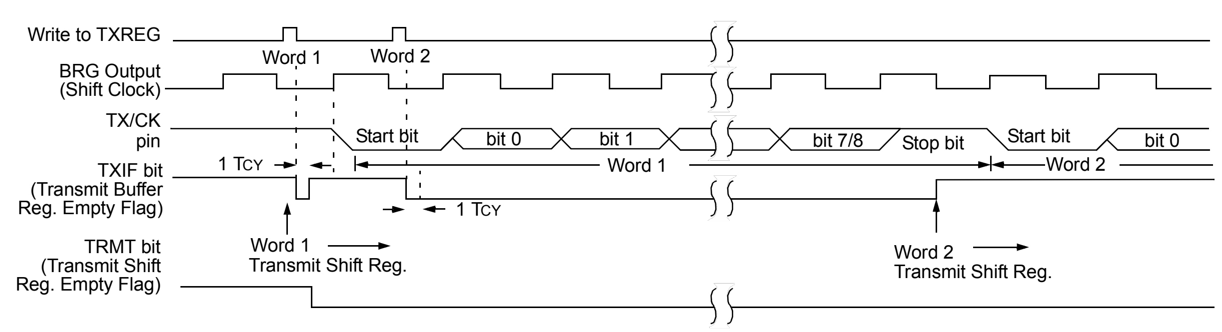


FIGURE 25-4: ASYNCHRONOUS TRANSMISSION (BACK-TO-BACK)



Note: This timing diagram shows two consecutive transmissions.

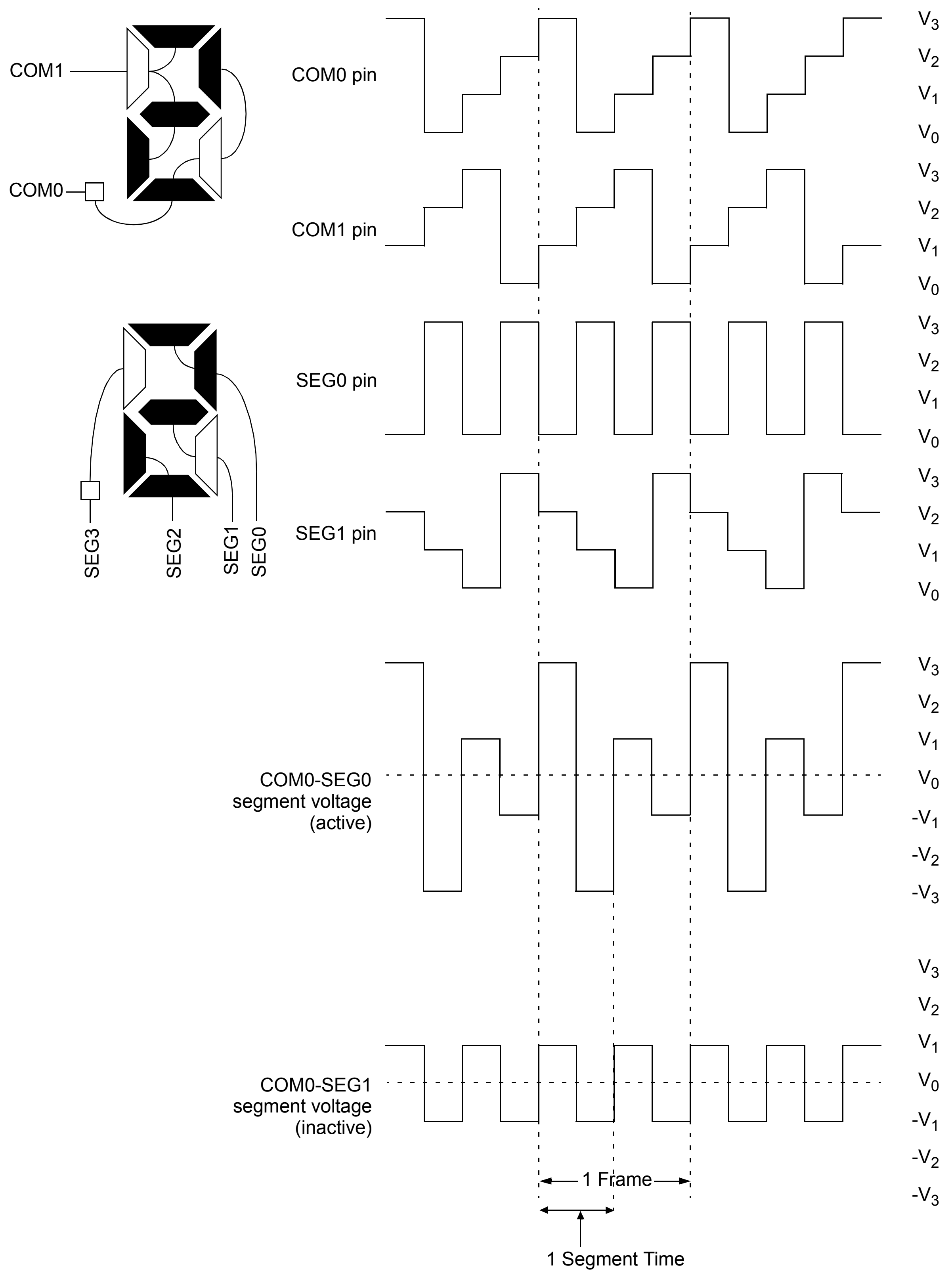
TABLE 25-2: SUMMARY OF REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	302
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	98
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	99
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	102
RCREG	EUSART Receive Data Register								296*
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	301
SPBRGL	BRG<7:0>								303*
SPBRGH	BRG<15:8>								303*
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	142
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	300

Legend: — = unimplemented, read as ‘0’. Shaded cells are not used for asynchronous reception.
* Page provides register information.

NOTES:

FIGURE 27-11: TYPE-A WAVEFORMS IN 1/2 MUX, 1/3 BIAS DRIVE



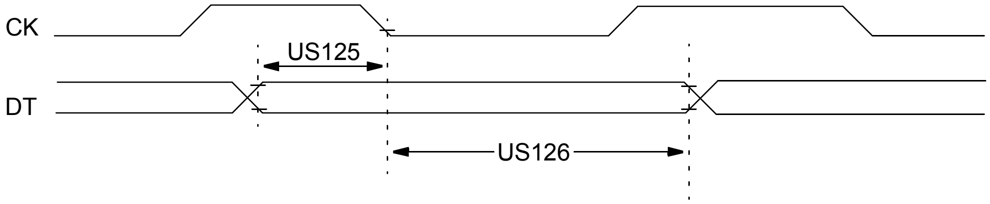
Note: 1 Frame = 2 single segment times.

TABLE 30-12: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)
Operating Temperature -40°C ≤ TA ≤ +125°C

Param. No.	Symbol	Characteristic		Min.	Max.	Units	Conditions
US120	TCKH2DTV	SYNC XMIT (Master and Slave) Clock high to data-out valid	3.0-5.5V	—	80	ns	
			1.8-5.5V	—	100	ns	
US121	TCKRF	Clock out rise time and fall time (Master mode)	3.0-5.5V	—	45	ns	
			1.8-5.5V	—	50	ns	
US122	TDTRF	Data-out rise time and fall time	3.0-5.5V	—	45	ns	
			1.8-5.5V	—	50	ns	

FIGURE 30-15: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 30-5 for load conditions.

TABLE 30-13: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)
Operating Temperature -40°C ≤ TA ≤ +125°C

Param. No.	Symbol	Characteristic	Min.	Max.	Units	Conditions
US125	TDTV2CKL	SYNC RCV (Master and Slave) Data-hold before CK ↓ (DT hold time)	10	—	ns	
US126	TCKL2DTL	Data-hold after CK ↓ (DT hold time)	15	—	ns	